# TLE7270-2

5-V Low Dropout Voltage Regulator

**Automotive Power** 



### 5-V Low Dropout Voltage Regulator

TLE7270-2





### 1 Overview

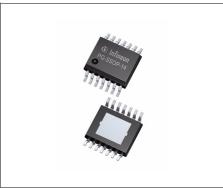
#### **Features**

- Ultra Low Current Consumption 20 μA
- Output Voltage 5 V ±2%
- · Output Current up to 300 mA
- · Power-On and Undervoltage Reset
- Reset Low Down to  $V_{\rm O}$  = 1 V
- · Very Low Dropout Voltage
- Output Current Limitation
- Overtemperature Shutdown
- Wide Temperature Range From -40 °C up to 150 °C
- Green Product (RoHS compliant)
- AEC Qualified

#### **Description**

The TLE7270-2 is a monolithic integrated low dropout voltage regulator for load currents up to 300 mA. An input voltage up to 42 V is regulated to  $V_{\rm Q,nom}=5.0~\rm V$  with a precision of  $\pm 2\%$ . Due to its integrated reset circuitry featuring power on timing and output voltage monitoring the IC is well suited as  $\mu$ -controller supply. The sophisticated design allows to achieve stable operation even with ceramic output capacitors down to 470 nF. The device is designed for the harsh environment of automotive applications. Therefore it is protected against overload, short circuit and overtemperature conditions by the implemented output current limitation and the overtemperature shutdown circuit. The TLE7270-2 can be also used in all other applications requiring a stabilized 5 V voltage.

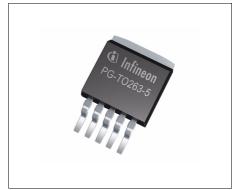
Due to its ultra low quiescent current of typically 20  $\mu$ A the TLE7270-2 is dedicated for use in applications permanently connected to  $V_{\rm BAT}$ . An integrated output sink current circuitry keeps the voltage at the Output pin Q below 5.5 V even in case of occuring reverse currents. Thus connected devices are protected from overvoltage damage. For applications requiring extremely low noise levels the Infineon voltage regulator family TLE 42XX and TLE 44XX is more suited than the TLE7270-2. A mV-range output noise on the TLE7270-2 caused by the charge pump operation is unavoidable due to the ultra low quiescent current concept.



PG-SSOP-14 Exposed Pad



PG-TO252-5



PG-TO263-5

Туре	Package	Marking
TLE7270-2E	PG-SSOP-14 Exposed Pad	7270-2E
TLE7270-2D	PG-TO252-5	7270-2D
TLE7270-2G	PG-TO263-5	7270-2G



**Block Diagram** 

## 2 Block Diagram

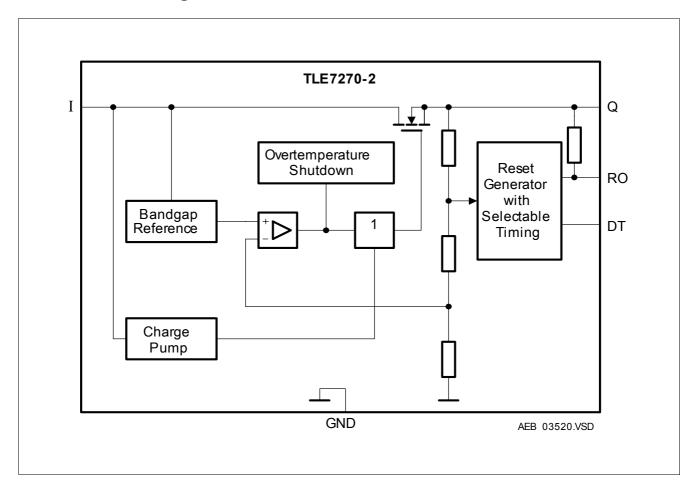


Figure 1 Block Diagram



**Pin Configuration** 

### 3 Pin Configuration

### 3.1 Pin Assignment PG-SSOP-14 Exposed Pad

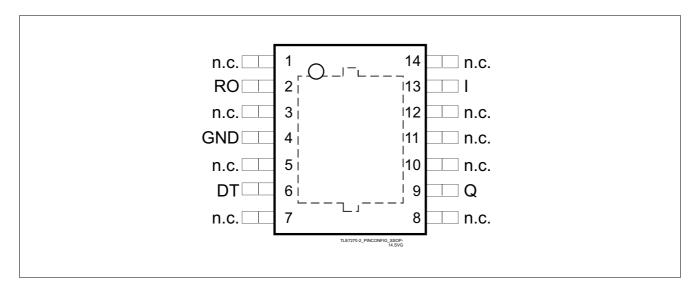


Figure 2 Pin Configuration (top view)

### 3.2 Pin Definitions and Functions PG-SSOP-14 Exposed Pad

Pin No.	Symbol	Function
1,3,5,7	n.c.	non connected
		can be open or connected to GND
2	RO	Reset Output
		open collector output with integrated pull-up resistor;
		optional external pull-up resistor of $\geq$ 10 k $\Omega$ to pin Q;
		leave open if reset function not needed
4	GND	Ground
6	DT	Delay Timing
		connect to GND or Q to choose the Power On Reset Delay Time
8,10,11,12,14	n.c.	non connected
		can be open or connected to GND
9	Q	Output
		block to ground with a capacitor close to the IC terminals, respecting the values given
		for its capacitance and ESR in "Functional Range" on Page 6
13	I	Input
		block to ground directly at the IC with a ceramic capacitor
Pad	_	Exposed Pad
		connect to GND and heatsink area



**Pin Configuration** 

### 3.3 Pin Assignment PG-TO252-5, PG-TO263-5

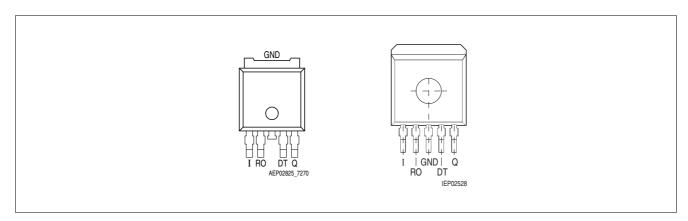


Figure 3 Pin Configuration (top view)

### 3.4 Pin Definitions and Functions PG-TO252-5, PG-TO263-5

Pin No.	Symbol	Function
1	I	Input block to ground directly at the IC with a ceramic capacitor
2	RO	Reset Output open collector output with integrated pull-up resistor; optional external pull-up resistor of $\geq$ 10 k $\Omega$ to pin Q; leave open if reset function not needed
3	GND	Ground internally connected to heat slug
4	DT	Delay Timing connect to GND or Q to choose the Power On Reset Delay Time
5	Q	Output block to ground with a capacitor close to the IC terminals, respecting the values given for its capacitance and ESR in "Functional Range" on Page 6
Heat Slug	-	Heat Slug internally connected to GND; connect to GND and heatsink area



**General Product Characteristics** 

### 4 General Product Characteristics

### 4.1 Absolute Maximum Ratings

### Absolute Maximum Ratings<sup>1)</sup>

 $T_i$  = -40 °C to 150 °C; all voltages with respect to ground, (unless otherwise specified)

Parameter	Symbol	Lin	nit Values	Unit	Test Condition
		Min.	Max.		
,	1	-	-		
Voltage	$V_1$	-0.3	45	V	_
Q, Reset Output RO, Delay Time	DT	-	<del>-                                    </del>		<u>'</u>
Voltage	$V_{\mathrm{Q}},V_{\mathrm{RO}},\ V_{\mathrm{DT}}$	-0.3	6	V	_
Voltage	$V_{\mathrm{Q}},V_{\mathrm{RO}},\ V_{\mathrm{DT}}$	-0.3	6.2	V	$t < 10 \text{ s}^{2)}$
rature	- 11			-	•
Junction temperature	$T_{i}$	-40	150	°C	_
Storage temperature	$T_{stg}$	-50	150	°C	_
sceptibility		-	<del>'</del>	,	•
Human Body Model (HBM) <sup>3)</sup>	Voltage	-	3	kV	_
Charged Device Model (CDM) <sup>4)</sup>	Voltage	-	1.5	kV	_
	Voltage  Q, Reset Output RO, Delay Time I Voltage  Voltage  rature  Junction temperature Storage temperature  ssceptibility  Human Body Model (HBM) <sup>3)</sup>	$\begin{array}{c c} & Voltage & V_{\rm I} \\ \hline \textbf{Q, Reset Output RO, Delay Time DT} \\ \hline Voltage & V_{\rm Q}, V_{\rm RO}, \\ \hline V_{\rm DT} \\ \hline Voltage & V_{\rm Q}, V_{\rm RO}, \\ \hline v_{\rm DT} \\ \hline \\ \textbf{rature} \\ \hline Junction temperature & T_{\rm j} \\ \hline Storage temperature & T_{\rm stg} \\ \hline \textbf{Isceptibility} \\ \hline \\ Human Body Model (HBM)^3) & Voltage \\ \hline \end{array}$		$\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$	$\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$

<sup>1)</sup> not subject to production test, specified by design

Note: Stresses above the ones listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note: Integrated protection functions are designed to prevent IC destruction under fault conditions described in the data sheet. Fault conditions are considered as "outside" normal operating range. Protection functions are not designed for continuous repetitive operation.

### 4.2 Functional Range

Pos.	Parameter	Symbol	Lim	it Values	Unit	Remarks
			Min.	Max.		
4.2.1	Input voltage	$V_1$	5.5	42	V	_
4.2.2	Output Capacitor's	$C_{Q}$	470	_	nF	1)
4.2.3	Requirements	$ESR(C_{Q})$	_	10	Ω	2)
4.2.4	Junction temperature	$T_{i}$	-40	150	°C	_

<sup>1)</sup> the minimum output capacitance requirement is applicable for a worst case capacitance tolerance of 30%

Note: Within the functional or operating range, the IC operates as described in the circuit description. The electrical characteristics are specified within the conditions given in the Electrical Characteristics table.

<sup>2)</sup> exposure to these absolute maximum ratings for extended periods (t > 10 s) may affect device reliability

<sup>3)</sup> ESD susceptibility Human Body Model "HBM" according to AEC-Q100-002 - JESD22-A114

<sup>4)</sup> ESD susceptibility Charged Device Model "CDM" according to ESDA STM5.3.1

<sup>2)</sup> relevant ESR value at f = 10 kHz



#### **General Product Characteristics**

### 4.3 Thermal Resistance

Note: This thermal data was generated in accordance with JEDEC JESD51 standards. For more information, go to www.jedec.org.

Pos.	Parameter	Symbol		Limit Val	ues	Unit	Conditions
			Min.	Тур.	Max.		
TLE72	70-2E (PG-SSOP-14 Exposed	Pad)					<u> </u>
4.3.1	Junction to Case <sup>1)</sup>	$R_{thJC}$	_	14	_	K/W	measured to
							exposed pad
4.3.2	Junction to Ambient <sup>1)</sup>	$R_{thJA}$	_	47	_	K/W	2)
4.3.3		$R_{thJA}$	_	141	_	K/W	footprint only <sup>3)</sup>
4.3.4		$R_{thJA}$	_	66	_	K/W	300 mm² heatsink area <sup>3)</sup>
4.3.5		$R_{thJA}$	_	56	_	K/W	600 mm² heatsink area <sup>3)</sup>
TLE72	70-2D (PG-TO252-5)	<u>'</u>	"		<u> </u>		1
4.3.1	Junction to Case <sup>1)</sup>	$R_{thJC}$	_	6	_	K/W	measured to tab
4.3.2	Junction to Ambient <sup>1)</sup>	$R_{thJA}$	_	32	_	K/W	2)
4.3.3		$R_{thJA}$	_	115	_	K/W	footprint only <sup>3)</sup>
4.3.4		$R_{thJA}$	_	62	_	K/W	300 mm² heatsink area <sup>3)</sup>
4.3.5		$R_{thJA}$	_	47	_	K/W	600 mm² heatsink area <sup>3)</sup>
TLE72	70-2G (PG-TO263-5)	<u> </u>		1	"	1	1
4.3.1	Junction to Case <sup>1)</sup>	$R_{thJC}$	_	6	_	K/W	measured to exposed pad
4.3.2	Junction to Ambient <sup>1)</sup>	$R_{thJA}$	_	27	_	K/W	2)
4.3.3		$R_{thJA}$	_	75	_	K/W	footprint only <sup>3)</sup>
4.3.4		$R_{thJA}$	_	47	_	K/W	300 mm² heatsink area <sup>3)</sup>
4.3.5		$R_{thJA}$	_	38	-	K/W	600 mm² heatsink area <sup>3)</sup>

<sup>1)</sup> Not subject to production test, specified by design.

<sup>2)</sup> Specified R<sub>thJA</sub> value is according to Jedec JESD51-2,-5,-7 at natural convection on FR4 2s2p board; The Product (Chip+Package) was simulated on a 76.2 x 114.3 x 1.5 mm³ board with 2 inner copper layers (2 x 70μm Cu, 2 x 35μm Cu). Where applicable a thermal via array under the exposed pad contacted the first inner copper layer.

<sup>3)</sup> Specified  $R_{\text{thJA}}$  value is according to Jedec JESD 51-3 at natural convection on FR4 1s0p board; The Product (Chip+Package) was simulated on a 76.2  $\times$  114.3  $\times$  1.5 mm<sup>3</sup> board with 1 copper layer (1 x 70 $\mu$ m Cu).



### 5 Electrical Characteristics

### 5.1 Electrical Characteristics Voltage Regulator

### **Electrical Characteristics**

 $V_{\rm i}$ =13.5 V;  $T_{\rm i}$  = -40 °C to 150 °C; all voltages with respect to ground (unless otherwise specified)

Pos.	Parameter	Symbol	Limit Values			Unit	<b>Measuring Condition</b>
			Min.	Тур.	Max.		
Output	Q			'			
5.1.1	Output Voltage	$V_{Q}$	4.9	5.0	5.1	V	0.1 mA < I <sub>Q</sub> <300 mA 6 V < V <sub>I</sub> < 16 V
5.1.2	Output Voltage	$V_{Q}$	4.9	5.0	5.1	V	0.1 mA < I <sub>Q</sub> <100 mA 6 V < V <sub>I</sub> < 40 V
5.1.3	Dropout Voltage	$V_{dr}$	_	250	500	mV	$I_{\rm Q}$ = 200 mA $V_{\rm dr}$ = $V_{\rm I} - V_{\rm Q}^{(1)}$
5.1.4	Load Regulation	$\Delta V_{ m Q,  lo}$	- 40	15	40	mV	$I_{\rm Q}$ = 5 mA to 250 mA
5.1.5	Line Regulation	$\Delta V_{Q, li}$	- 20	5	20	mV	$V_{\rm I}$ = 10 V to 32 V $I_{\rm Q}$ = 5 mA
5.1.6	Output Current Limitation	$I_{Q}$	301	_	_	mA	1)
5.1.7	Output Current Limitation	$I_{Q}$	_	_	800	mA	$V_{\rm Q}$ = 0V
5.1.8	Power Supply Ripple Rejection <sup>2)</sup>	PSRR	_	60	_	dB	$f_{\rm r}$ = 100 Hz; $V_{\rm r}$ = 0.5 Vpp
5.1.9	Temperature Output Voltage Drift	$\frac{dV_{Q}}{dT}$	_	0.5	_	mV/K	-
Curren	t Consumption			'			
5.1.10	Quiescent Current $I_q = I_l - I_Q$	$I_{q}$	_	20	30	μΑ	$I_{\rm Q}$ = 0.1 mA $T_{\rm j}$ = 25 °C
5.1.11	Quiescent Current $I_q = I_l - I_Q$	$I_{q}$	_	-	40	μΑ	$I_{\rm Q}$ = 0.1 mA $T_{\rm j} \le$ 80 °C

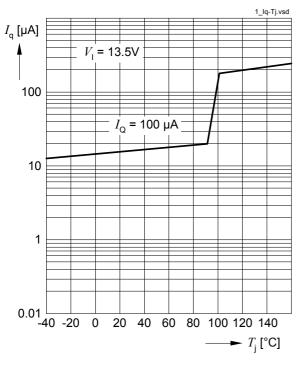
<sup>1)</sup> Measured when the output voltage  $V_{\rm Q}$  has dropped 100 mV from the nominal value obtained at  $V_{\rm I}$  = 13.5 V.

<sup>2)</sup> not subject to production test, specified by design

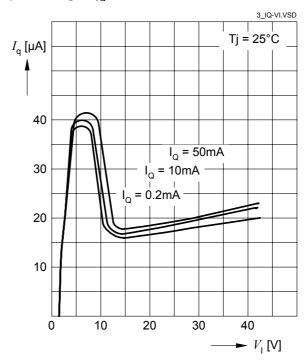


### 5.2 Typical Performance Characteristics Voltage Regulator

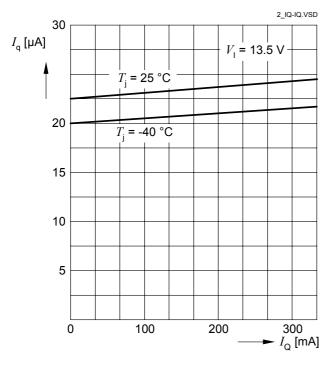
## Current Consumption $I_{\rm q}$ versus Junction Temperature $T_{\rm J}$



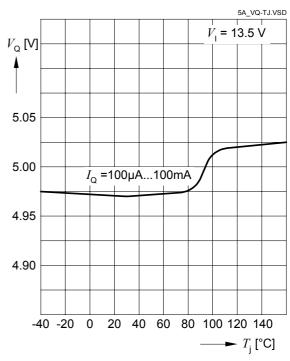
# Current Consumption $I_{\rm q}$ versus Input Voltage $V_{\rm IQ}$



## Current Consumption $I_{\rm q}$ versus Output Current $I_{\rm Q}$

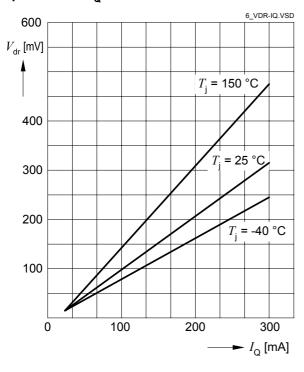


# Output Voltage $V_{\rm Q}$ versus Junction Temperature $T_{\rm J}$

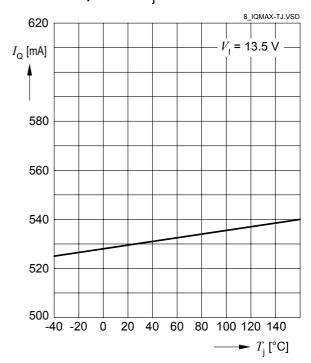




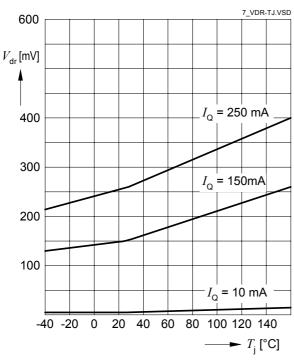
## Dropout Voltage $V_{\mathrm{dr}}$ versus Output Current $I_{\mathrm{Q}}$



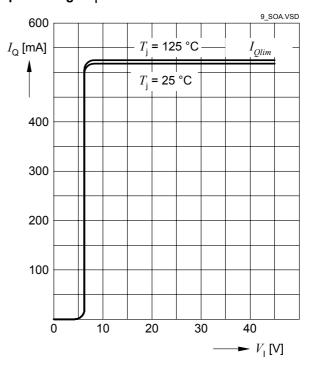
### 



## Dropout Voltage $V_{\mathrm{dr}}$ versus Junction Temperature

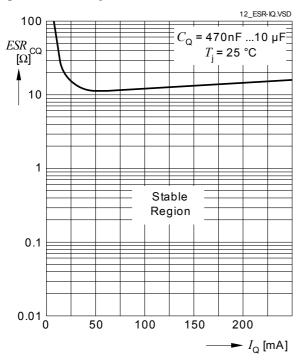


## Maximum Output Current $I_{\mathrm{Q}}$ versus Input Voltage $V_{\mathrm{I}}$

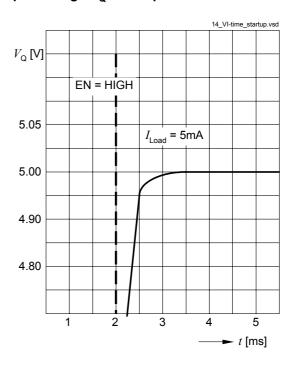




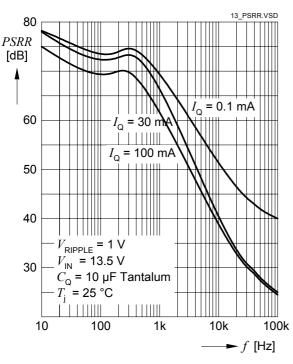
### **Region of Stability**



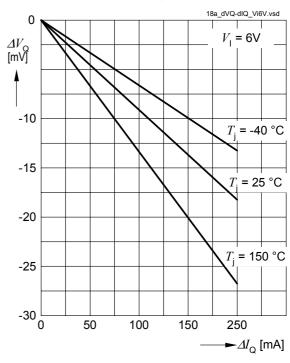
### Output Voltage $V_{\mathsf{Q}}$ Start-up behavior



## Power Supply Ripple Rejection PSRR versus Frequency f

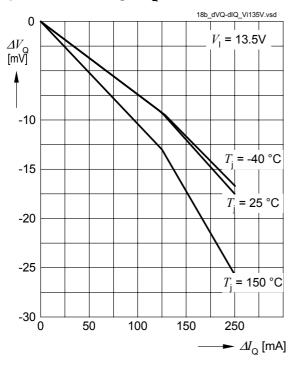


## Load Regulation $\Delta V_{\mathrm{Q}}$ versus Output Current Change $\Delta I_{\mathrm{Q}}$

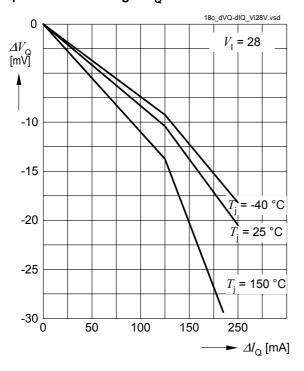




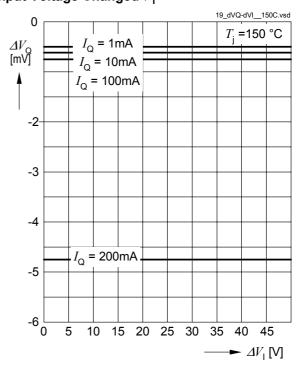
## Load Regulation $\Delta V_{\rm Q}$ versus Output Current Change $dI_{\rm Q}$



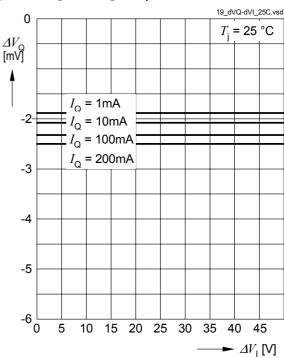
# Load Regulation $\Delta V_{\rm Q}$ versus Output Current Change $\Delta I_{\rm Q}$



## Line Regulation $\Delta V_{\mathrm{Q}}$ versus Input Voltage Changed $V_{\mathrm{I}}$

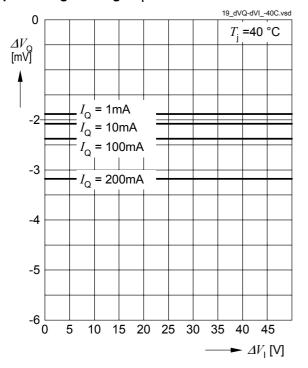


## Line Regulation $\Delta V_{\mathrm{Q}}$ versus Input Voltage Changed $V_{\mathrm{I}}$

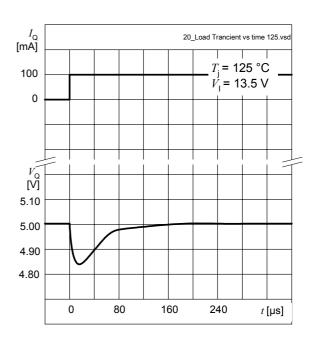




## Line Regulation $\Delta V_{\rm Q}$ versus Input Voltage Change $V_{\rm I}$

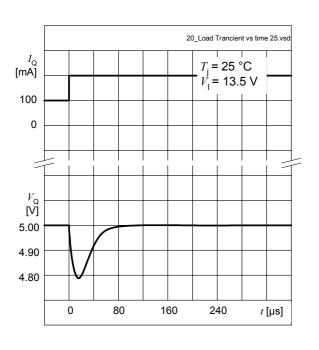


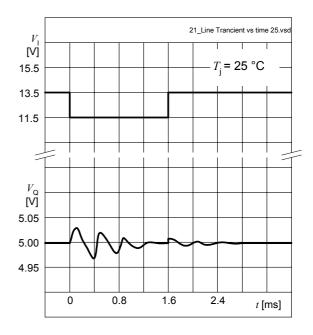
### Load Transient Response Peak Voltage $\Delta V_{ m Q}$



Load Transient Response Peak Voltage  $\Delta V_{
m Q}$ 



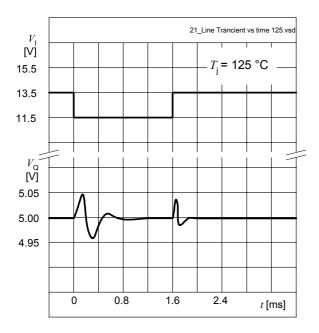






### Line Transient Response Peak Voltage $\Delta V_{\mathrm{Q}}$





#### 5.3 Electrical Characteristics Reset Function

The Reset function informs e.g. the microcontroller in case the output voltage has fallen below the lower threshold **VRT** of typ. 4.65 V. The headroom **VRH** between the output voltage and the reset threshold is typically 350 mV. Connecting the regulator to a battery voltage at first the reset signal remains LOW. When the output voltage has reached the reset threshold **VRT** the reset output RO remains still LOW for the reset delay time **tRD**. Afterwards the reset output turns HIGH.

#### **Electrical Characteristics Reset**

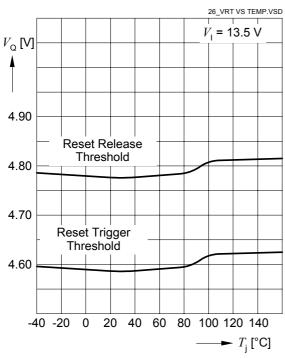
 $V_1$ =13.5 V; – 40 °C <  $T_1$ < 150 °C; all voltages with respect to ground (unless otherwise specified)

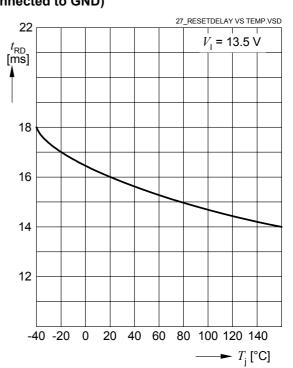
Pos.	Parameter	Symbol	Limit Values			Unit	Conditions
			Min.	Тур.	Max.		
5.3.1	Output Undervoltage Reset Switching Threshold	$V_{RT}$	4.50	4.65	4.80	V	$V_{\rm Q}$ decreasing $V_{\rm I}$ = 6V
5.3.2	Output Undervoltage Reset Headroom	$V_{RH}$	-	350	-	mV	_
5.3.3	Reset Output Low Level Voltage	$V_{ROL}$	_	0.2	0.4	V	$R_{\rm RO}$ = 10 k $\Omega$ ; $V_{\rm Q}$ > 1 V
5.3.4	Integrated Reset Pull Up Resistor	$R_{RO}$	15	30	45	kΩ	_
5.3.5	Optional External Reset Pull Up Resistor	$R_{RO,ext}$	10	-	-	kΩ	_
5.3.6	Power On Reset Delay Time	$t_{RD}$	10	16	22	ms	pin DT connected to GND
5.3.7	Power On Reset Delay Time	$t_{RD}$	80	128	176	ms	pin DT connected to Q
5.3.8	Reset Reaction Time	$t_{RR}$	_	_	12	μs	_



### 5.4 Typical Performance Characteristics Reset Function

Reset Threshold  $V_{\rm RT}$  versus Junction Temperature Reset Delay  $t_{\rm RD}$  versus Junction Temperature  $T_{\rm J}$  at fast timing (DT connected to GND)





**Package Outlines** 

### 6 Package Outlines

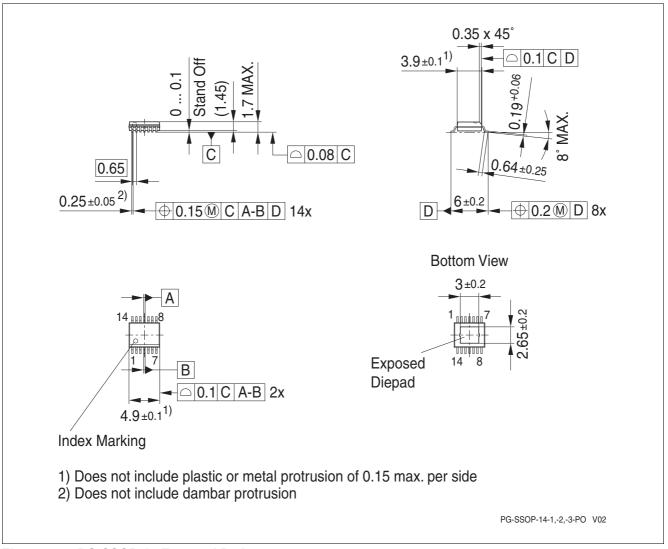


Figure 4 PG-SSOP-14 Exposed Pad



**Package Outlines** 

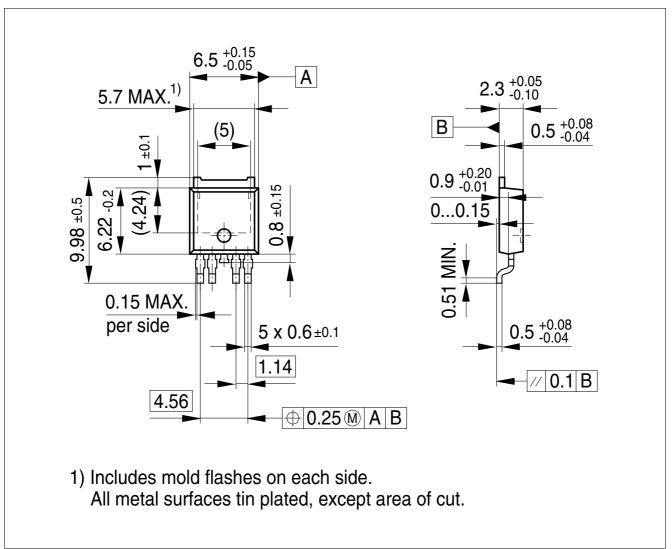


Figure 5 PG-TO252-5



#### **Package Outlines**

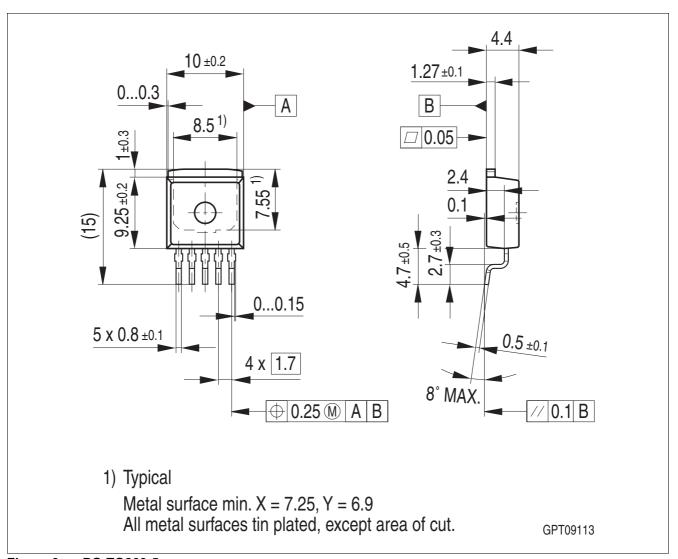


Figure 6 PG-TO263-5

### **Green Product (RoHS compliant)**

To meet the world-wide customer requirements for environmentally friendly products and to be compliant with government regulations the device is available as a green product. Green products are RoHS-Compliant (i.e Pb-free finish on leads and suitable for Pb-free soldering according to IPC/JEDEC J-STD-020).



**Revision History** 

## 7 Revision History

Revision	Date	Changes	
1.01	2009-07-23	updated version data sheet:	
		in "Electrical Characteristics Voltage Regulator" on Page 8, former Item 5.1.12 "Current Consumption, Regulator Disabled" removed, in Condition of Item 5.1.10 and Item 5.1.11 " $V_{\rm EN}$ = 5 V" removed: Non relevant information as TLE7270-2 does not implement Enable Feature	
1.0	2009-06-01	initial version data sheet	

Edition 2009-07-23

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